

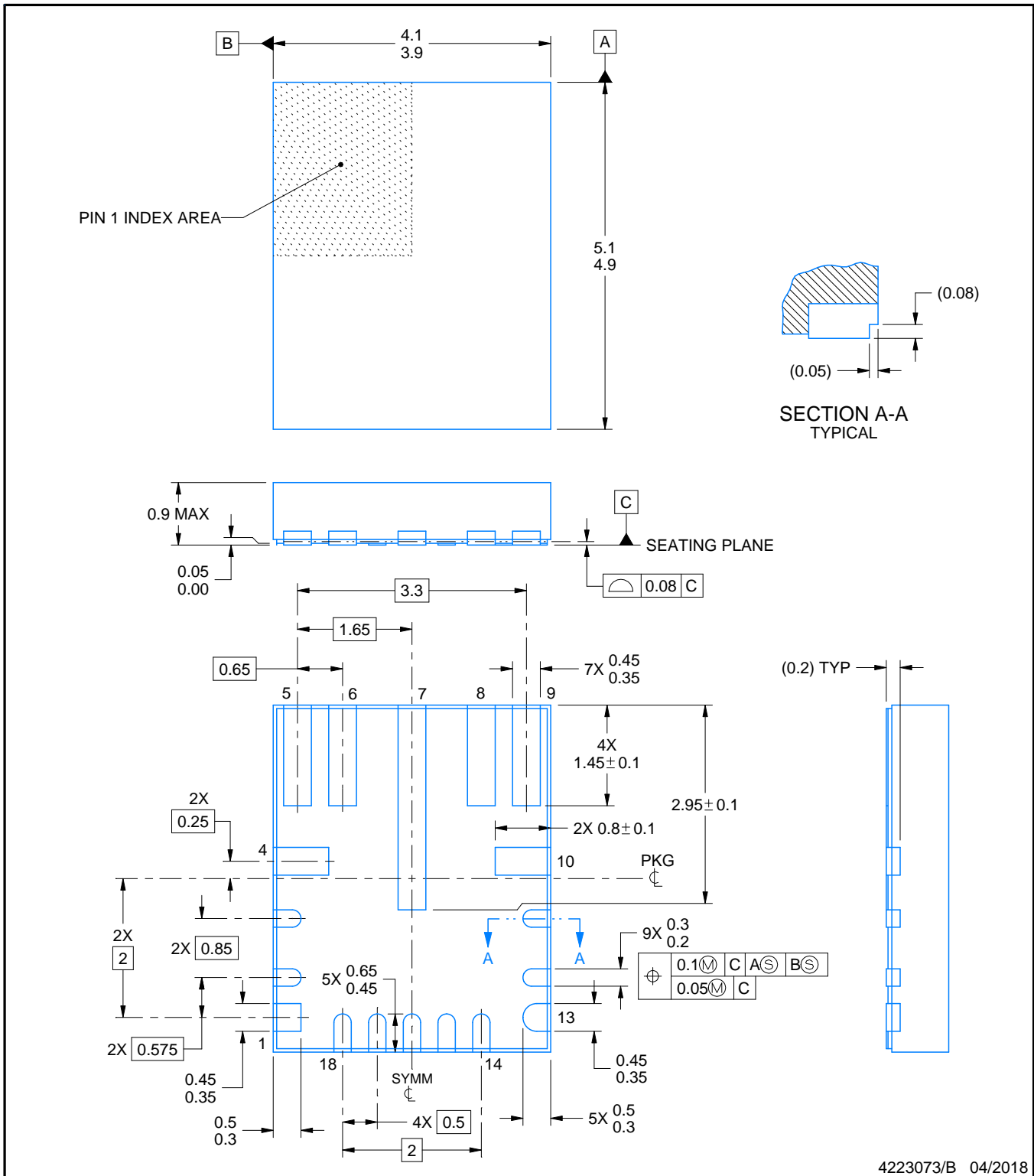
RNL0018A



PACKAGE OUTLINE

VQFN-HR - 0.9 mm max height

PLASTIC QUAD FLATPACK - NO LEAD



4223073/B 04/2018

NOTES:

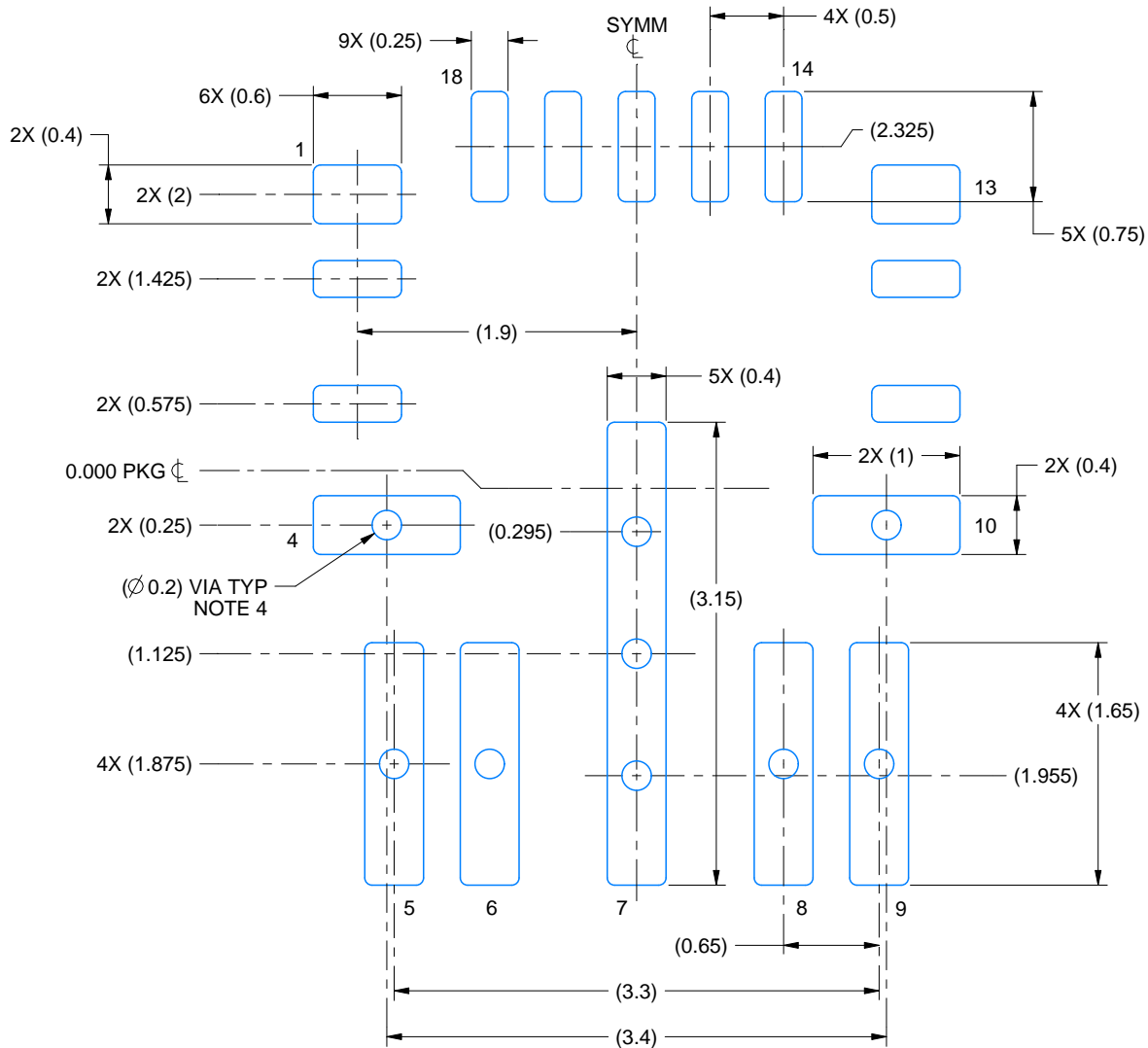
1. All linear dimensions are in millimeters. Any dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
2. This drawing is subject to change without notice.

EXAMPLE BOARD LAYOUT

RNL0018A

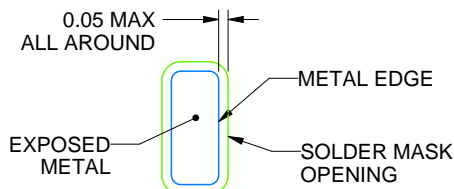
VQFN-HR - 0.9 mm max height

PLASTIC QUAD FLATPACK - NO LEAD



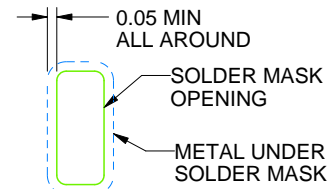
LAND PATTERN EXAMPLE

EXPOSED METAL SHOWN
SCALE:20X



NON SOLDER MASK
DEFINED
(PREFERRED)

SOLDER MASK DETAILS



SOLDER MASK
DEFINED

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NOTES: (continued)

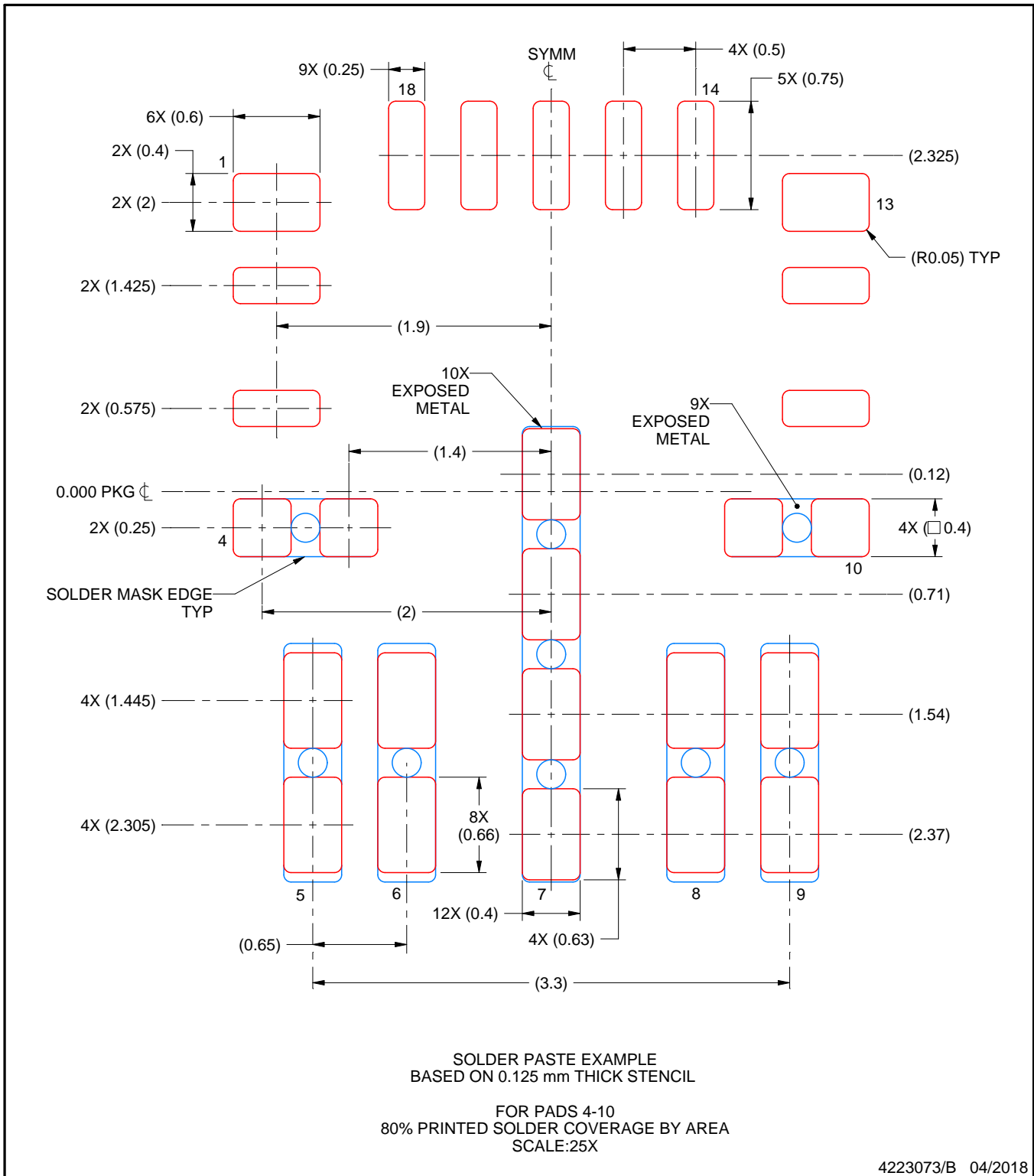
- This package is designed to be soldered to thermal pads on the board. For more information, see Texas Instruments literature number SLUA271 (www.ti.com/lit/slua271).
- Vias are optional depending on application, refer to device data sheet. If any vias are implemented, refer to their locations shown on this view. It is recommended that vias under paste be filled, plugged or tented.

EXAMPLE STENCIL DESIGN

RNL0018A

VQFN-HR - 0.9 mm max height

PLASTIC QUAD FLATPACK - NO LEAD



NOTES: (continued)

5. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.

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